



TSM16C

16-CH Auto Sensitivity Calibration Capacitive Touch Sensor

SPECIFICATION VER. 1.5



# **Revision History**

Rev.	Description of change	Date	Originator
0.9	First Creation	16.03.15	CH LEE
0.91	Operation Supply Voltage modify	16.03.28	CH LEE
0.92	Mechanical Drawing modify	16.04.01	CH LEE
1.0	Current Consumption modify	16.06.30	CH LEE
1.1	Spec. format modify	16.10.26	CH LEE
1.2	Control register wrong name modify	17.07.14	CH LEE
1.3	A Few Contents modify 1. Pin Configuration 2. Cdeg remove 3. IRBIAS remove 4. RND cap. Remove 5. Single/Multi. Touch detection mode control added	18.04.02	CH LEE
1.4	Typing Mistake modify	18.06.07	CH LEE
1.5	Single/Multi. Control Register default value modify	18.07.03	CH LEE



## General

The TSM16C is 16-Channel capacitive sensor with auto sensitivity calibration. And the supply voltage range is from 1.8 to 5.0V.

The TSM16C has the SLEEP mode to save the consumption. And the current consumption is 8 uA.

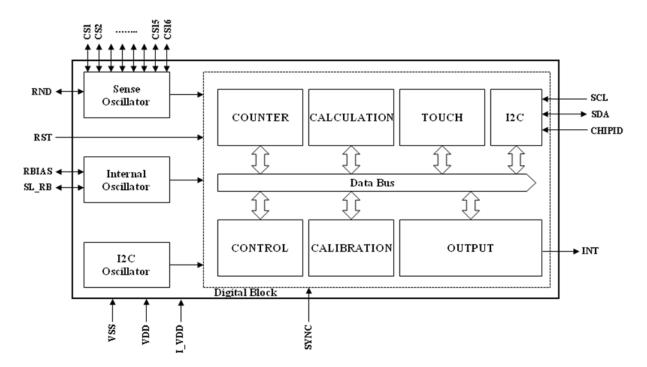
The TSM16C offers fast touch detection with fast response operation.

The result of touch sensing can be checked by the I<sup>2</sup>C serial interface. And touch intensity can be detectable within 3 steps (Low, Middle and High).

## **Block Diagram**

## **Feature**

- 16-Channel capacitive sensor with auto sensitivity calibration
- Selectable output operation (single mode / multimode)
- Independently adjustable in 8 step sensitivity
- Adjustable internal frequency with external resister
- Adjustable response time and interrupt level by the control registers
- I2C serial interface
- Embedded high frequency noise elimination circuit
- Typical current consumption xxx 45 uA (@3.0V)
- Sleep mode current consumption 8 uA (@3.0V)
- RoHS compliant 28QFN package



## **Application**

- Mobile application (mobile phone / PDA / PMP etc)
- Membrane switch replacement
- Sealed control panels, keypads
- Door key-lock matrix application
- Touch screen replacement application

## **Ordering Information**

Part No.	Package
TSM16C	28 QFN





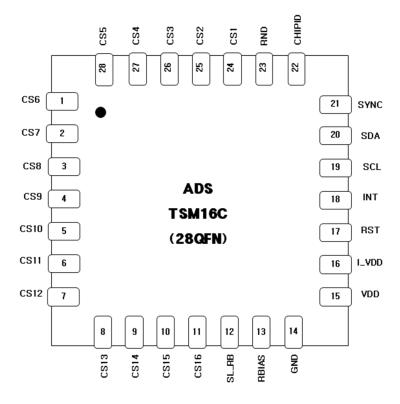
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# **Pin Configuration**



TSM16C (28 QFN)

# 2 Pin Description

## VDD, VSS

Supply voltage and ground pin.

#### I VDD

Supply voltage pin for IO pads.

#### RND

Reference channel capacitive sensor input pin.

## **CS1 ~ CS16**

Capacitive sensor input pins.

#### SCL. SDA

SCL is I<sup>2</sup>C clock input pin and SDA is I<sup>2</sup>C data input-output pin.

#### INT

Touch sensing interrupt output pin.

#### RBIAS

Internal bias adjust input.

#### SL RB

Internal bias adjust input for the SLEEP mode.

## **RST**

System reset input.

## **CHIPID**

I2C address selection input.

## **SYNC**

Sync pulse input/output for the sync operation.





# 2.1 Pin Map (28 QFN package)

Pin Number	Name	I/O	Description	Protection
PIN No.	Name	I/O	Description	Protection
1	CS6	Analog Input	CH6 capacitive sensor input	VDD/GND
2	CS7	Analog Input	CH7 capacitive sensor input	VDD/GND
3	CS8	Analog Input	CH8 capacitive sensor input	VDD/GND
4	CS9	Analog Input	CH9 capacitive sensor input	VDD/GND
5	CS10	Analog Input	CH10 capacitive sensor input	VDD/GND
6	CS11	Analog Input	CH11 capacitive sensor input	VDD/GND
7	CS12	Analog Input	CH12 capacitive sensor input	VDD/GND
8	CS13	Analog Input	CH13 capacitive sensor input	VDD/GND
9	CS14	Analog Input	CH14 capacitive sensor input	VDD/GND
10	CS15	Analog Input	CH15 capacitive sensor input	VDD/GND
11	CS16	Analog Input	CH16 capacitive sensor input	VDD/GND
12	SL_RB	Analog Input	SLEEP Mode Internal bias adjust input	VDD/GND
13	RBIAS	Analog Input	Internal bias adjust input	VDD/GND
14	GND	Ground	Supply ground	VDD
15	VDD	Power	Power	GND
16	I_VDD	Power	IO PAD Power	GND
17	RST	Digital Input	System reset (High reset)	VDD/GND
18	INT	Digital Output	Interrupt output (Open drain)	VDD/GND
19	SCL	Digital Input	I2C clock input	VDD/GND
20	SDA	Digital Input/Output	I2C data (Open drain)	VDD/GND
21	SYNC	Digital Input/Output	Sync pulse input /output	VDD/GND
22	CHIPID	Digital Input	I2C address selection	VDD/GND
23	RND	Analog Input	Ref. Ch capacitive sensor input	VDD/GND
24	CS1	Analog Input	CH1 capacitive sensor input	VDD/GND
25	CS2	Analog Input	CH2 capacitive sensor input	VDD/GND
26	CS3	Analog Input	CH3 capacitive sensor input	VDD/GND
27	CS4	Analog Input	CH4 capacitive sensor input	VDD/GND





# **Absolute Maximum Rating**

Maximum supply voltage VDD+0.3 Maximum voltage on any pin Maximum current on any PAD 100mA Power Dissipation 800mW -50 ~ 150℃ Storage Temperature Operating Temperature -40 ~ 85 °C Junction Temperature 150℃

Note Unless any other command is noted, all above are operated in normal temperature.

## **ESD & Latch-up Characteristics**

## **ESD Characteristics**

Mode	Polarity	Max	Reference
		8000V	VDD
H.B.M	Pos / Neg	8000V	VSS
		8000V	P to P
		400V	VDD
M.M	Pos / Neg	400V	VSS
		400V	P to P
CDM	Dec / Nec	800V	DIDECT
C.D.M	Pos / Neg	800V	DIRECT

## 4.2 Latch-up Characteristics

Mode	Polarity	Max	Test Step	
LTost	Positive	200mA	25 m A	
I Test	Negative	-200mA	- 25mA	
V supply over 5.0V	Positive	8.25V	1.0V	



## 5 Electrical Characteristics

•  $V_{DD}$ =3.3V, Rb=510k, Sync Mode (Rsync = 2M $\Omega$ ) (Unless otherwise noted),  $T_A$  = 25 °C

Characteristics Symbol Test Condition		Min	Тур	Max	Units		
Power supply requirement and	d current co	onsumption					
Operating supply voltage	$V_{DD}$		1.8	3.3	5.0	V	
		$V_{DD}$ = 3.3V $R_B$ =510k $R_SB$ =0	-	25	-		
Cument consumntion	T	$V_{DD} = 5.0 V R_B = 510 k R_S B = 0$	-	46	-		
Current consumption	$I_{DD}$	$V_{DD} = 3.3 V R_B = 510 k R_S B = 2M$	-	8	-	μΑ	
		$V_{DD} = 5.0 V R_B = 510 k R_S B = 2M$	-	18	-		
Touch sensing performance							
Minimum detective capacitance difference	ΔC	Cs = 10pF (I2C default sensitivity select)	0.2	-	-	рF	
Sense input capacitance range (Note1)	$C_{S}$		-	10	100	рF	
Sense input resistance range	$R_S$		-	200	1000	Ω	
Output impedance (open drain)	Zo	$\Delta C > 0.2 \text{pF}, \text{ Cs} = 10 \text{pF},$ (I2C default sensitivity select)	-	12	-		
		$\Delta C < 0.2 \text{pF}, \text{ Cs} = 10 \text{pF},$ (I2C default sensitivity select)	-	30M	-	Ω	
		$V_{DD} = 5.0 V R_B = 510 k$	-	80	-		
System performance					ı	ı	
External reset high pulse width	V <sub>DD_RST</sub>	T <sub>A</sub> = 25 ℃	10	-	-	ms	
Self calibration time after	$T_{CAL}$	$V_{DD} = 3.3 V R_B = 510 k$	- 100 -		ms		
system reset	1 CAL	$V_{DD} = 5.0 V R_B = 510 k$	-	80	-	1113	
Output maximum sink current	$I_{OUT}$	$T_A = 25^{\circ}\text{C}$	-	-	4.0	mA	
Recommended bias resistance	$R_{B}$	$V_{DD} = 3.3V$	200	510	820	kΩ	
range (Note2)	_	$V_{DD} = 5.0V$	330	620	1200		
Maximum bias capacitance	$C_{B\_MAX}$		-	820	1000	pF	
Recommended sync resistance range	R <sub>SYNC</sub>		1	2	20	ΜΩ	
Max. I <sup>2</sup> C SCL clock speed	$f_{SCL\_MAX}$		-	-	400	KHz	

**Note 1**: The sensitivity can be increased with lower  $C_S$  value.

The recommended value of  $C_S$  is 10pF when using 3T PC(Poly Carbonate) cover and 10 mm  $\,$  x 7 mm touch pattern.

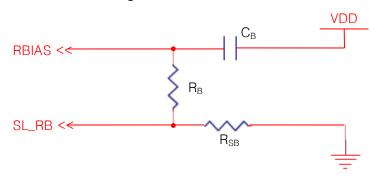
**Note 2**: The lower  $R_B$  is recommended in noisy condition.





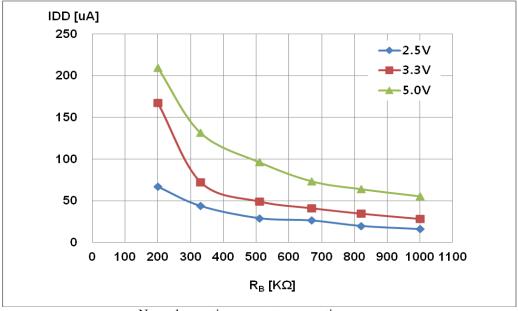
## **6 TSM16C Implementation**

## 6.1 RBIAS & SL\_RB implementation



The RBIAS is connecting to the resistor to decide the oscillator and internal bias current. The sensing frequency, internal clock frequency and current consumption are therefore able to be adjusted with  $R_B$ . A voltage ripple on RBIAS can make critical internal error, so  $C_B$  is connected to the VDD (not GND) is recommended. (The typical value of  $C_B$  is 820pF and the maximum Value is 1nF.)

The  $R_{SB}$  should be connected as above figure when the TSM16C operates in SLEEP Mode to save the current consumption. In this case, the consumption depends on the sum of the serial resistors and the response time might be longer.



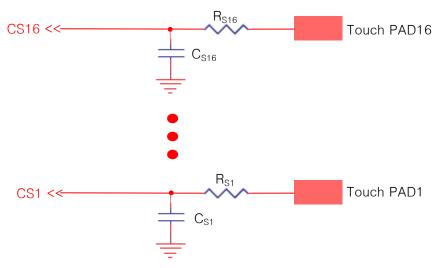
Normal operation current consumption curve

The current consumption curve of TSM16C is represented in accordance with  $R_{\rm B}$  value as above. The lower  $R_{\rm B}$  requires more current consumption but it is recommended in noisy application. For example, refrigerator, air conditioner and so on.





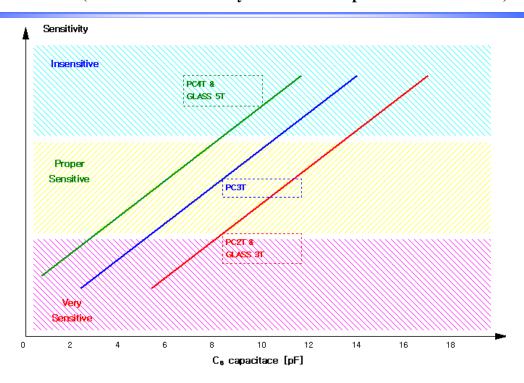
## 6.2 CS implementation



The TSM16C has basically eight steps sensitivity, which is available to control with internal register by I2C interface. The parallel capacitor  $C_{S1}$  is added to CS1 and  $C_{S16}$  to CS16 to adjust sensitivity. The sensitivity will be increased when smaller value of  $C_S$  is used. (Refer to the below Sensitivity Example Figure) It could be useful in case detail sensitivity mediation is required. The internal touch decision process of each channel is separated from each other. The twelve channel touch key board application can therefore be designed by using only one TSM16C without coupling problem. The  $R_S$  is serial connection resistor to avoid mal-function from external surge and ESD. (It might be optional.) From  $200\Omega$  to  $1k\Omega$  is recommended for  $R_S$ . The size and shape of PAD might have influence on the sensitivity. The sensitivity will be optimal when the size of PAD is approximately an half of the first knuckle (it's about  $10 \text{ mm} \times 7 \text{ mm}$ ). The connection line of CS1 ~ CS16 to touch PAD is recommended to be routed as short as possible to prevent from abnormal touch detect caused by connection line. The unused CS pin must be disable using control registers.





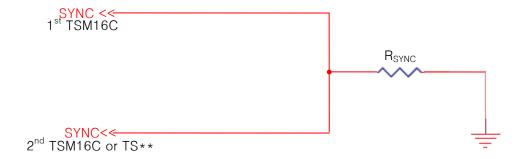


Sensitivity example figure with default sensitivity selection

## 6.3 SYNC implementation

## 6.3.1 Multi Chip Application

Over two TSM16C can work on the one application at the same time thanks to SYNC function with this pin. The SYNC pulse prevents over two sensing signal from interfering with each other.  $R_{SYNC}$  is pull-down resistor of SYNC pin. Too big value of  $R_{SYNC}$  makes the SYNC pulse falling delay, and too small value of  $R_{SYNC}$  makes rising delay. Typical value of  $R_{SYNC}$  is  $2M\Omega$ . The Sync pin should be implemented as below. The TSM16C can also be used with the other TSxx series by employing this SYNC function.

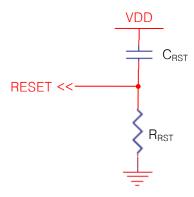






## **6.4 RESET implementation**

TSM16C has internal data latches, so initial state of these latches must be reset by external reset pulse before normal operation starts. The reset pulse can be controlled by host MCU directly or other reset device. If not, the circuit should be composed as below figure. The reset pulse must have high pulse duration about a few msec to cover power VDD rising time. The recommended value of  $R_{RST}$  and  $C_{RST}$  are 330K $\Omega$  and 100nF.



Recommended reset circuits 1

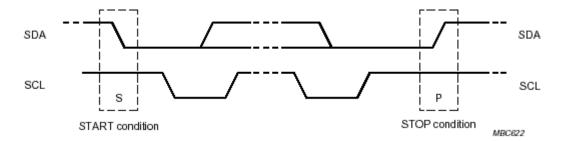




# 7 I<sup>2</sup>C Interface

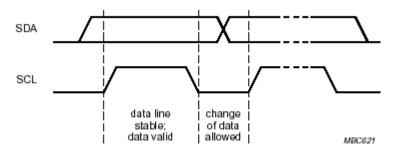
## 7.1 Start & Stop Condition

- **◀** Start Condition (S)
- **◀** Stop Condition (P)
- Repeated Start (Sr)



## 7.2 Data validity

The SDA should be stable when the SCL is high and the SDA can be changed when the SCL is low.

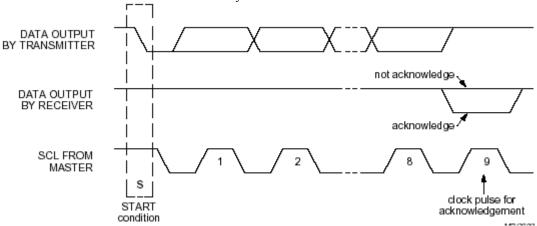


## 7.3 Byte Format

The byte structure is composed with 8Bit data and an acknowledge signal.

## 7.4 Acknowledge

It is a check bit whether the receiver gets the data from the transmitter without error or not. The receiver will write '0' when it received the data successfully and '1' if not.





## 7.5 First Byte

#### 7.5.1 Slave Address

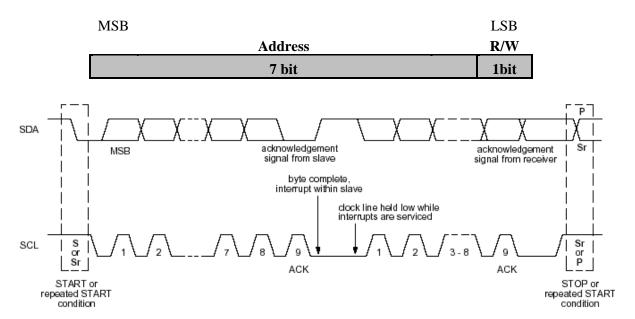
It is the first byte from the start condition. It is used to access the slave device.

**TSM16C Chip Address: 7bit** 

CHIPID	Address
GND	0xD0
VDD	0xF0

### 7.5.2 R/W

The direction of data is decided by the bit and it follows the address data.



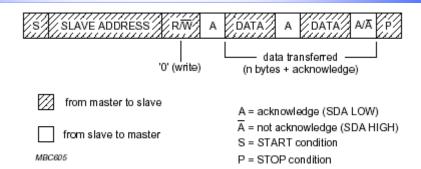
## 7.6 Transferring Data

## 7.6.1 Write Operation

The byte sequence is as follows:

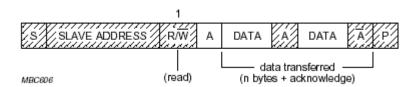
- the first byte gives the device address plus the direction bit (R/W = 0).
- the second byte contains the internal address of the first register to be accessed.
- the next byte is written in the internal register. Following bytes are written in successive internal registers.
- the transfer lasts until stop conditions are encountered.
- the TSM16C acknowledges every byte transfer.



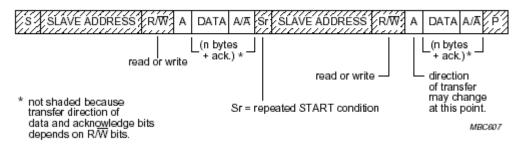


## 7.6.2 Read Operation

The address of the first register to read is programmed in a write operation without data, and terminated by the stop condition. Then, another start is followed by the device address and R/W= 1. All following bytes are now data to be read at successive positions starting from the initial address.



## 7.6.3 Read/Write Operation



# 7.7 I<sup>2</sup>C write and read operations in normal mode

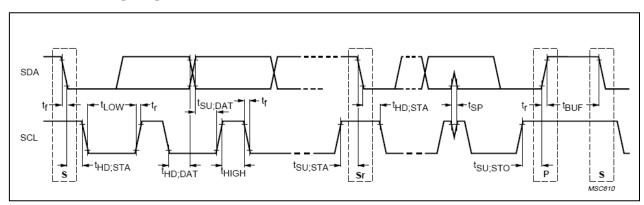
The following figure represents the I<sup>2</sup>C normal mode write and read registers.

Start	Device Address 0xD0	ACK	Register Address 0x00	ACK	Data AA	ACK	Data BB	ACK	Stop
Read re	egister 0x00 and	0x01							_
Start	Device Address 0xD0	ACK	Register Address 0x00	ACK	Stop				
Start	Device	ACK	Data Read AA	ACK	Data Read BB	ACK	Stop		
	Address 0xD1 ACK Data Read BB ACK Stop								
	From Maste	r to Slav	e	From Sla	ave to Master				





# 7.8 I<sup>2</sup>C timing diagram



DADAMETED	CVMDOI	1001	kbps	4001	TINITE	
PARAMETER	SYMBOL	MIN.	MAX.	MIN.	MAX.	UNIT
Hold time (repeated)START condition.	tHD;STA	4.0	-	0.6	-	us
LOW period of the SCL clock	tLOW	4.7	-	1.3	-	us
HIGH period of the SCL clock	tHIGH	4.0	-	0.6	-	us
Set-up time for a repeated START condition	tSU;STA	4.7	-	0.6	-	us
Data hold time	tHD;DAT	1.0	-	-	-	us
Data set-up time	tSU;DAT	250	-	100	-	ns
Rise time of both SDA and SCL signals	tr	-	1000	20	300	ns
Fall time of both SDA and SCL signals	tf	-	300	20	300	ns
Set-up time for STOP condition	tSU;STO	4.0	-	0.6	-	us
Bus free time between a STOP and START condition	tBUF	4.7	-	1.3	-	us
Noise margin at the LOW level for each connected device	VnL	0.1VDD	-	0.1VDD	-	V
Noise margin at the HIGH level for each connected device	VnH	0.2VDD	-	0.2VDD	-	V
Input Low level				0	V <sub>DD</sub> *0.2	V
Input High level				V <sub>DD</sub> *0.8	$V_{ m DD}$	V



## 8 TSM16C control register

- ◀ Note: The unused bits (defined as reserved) in I℃ registers must be kept to default values.
- ◀ Note: The bit0 and bit1 of CTRL2 register must be written by 0b11 after power on during an initialize phase. (Refer to the chapter 9. initialize flow)
- Note: HS (High Sensitivity) / MS (Middle Sensitivity) / LS (Low Sensitivity)
- ◀ Note: Low Output (light touch) / Middle Output (middle touch) / High Output (hard touch)

## 8.1 I<sup>2</sup>C Register Map

Nama	Addr.	Reset Value	Register Function and Description								
Name	(Hex)	(Bin)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Sensitivity1	02h	1011 1011	Ch2HL		Ch2M		Ch1HL		Ch1M		
Sensitivity2	03h	1011 1011	Ch4HL		Ch4M		Ch3HL		Ch3M		
Sensitivity3	04h	1011 1011	Ch6HL		Ch6M		Ch5HL		Ch5M		
Sensitivity4	05h	1011 1011	Ch8HL		Ch8M		Ch7HL		Ch7M		
Sensitivity5	06h	1011 1011	Ch10HL		Ch10M		Ch9HL		Ch9M		
Sensitivity6	07h	1011 1011	Ch12HL		Ch12M		Ch11HL	Ch11M			
Sensitivity7	22h	1011 1011	Ch14HL		Ch14M		Ch13HL	Ch13M			
Sensitivity8	23h	1011 1011	Ch16HL		Ch16M		Ch15HL	Ch15M			
CTRL1	08h	0010 0010	MS	F	ГС	II	.C	RTC			
CTRL2	09h	0000 0001	0	0	MULTI	IMP_SEL	SRST	SLEEP	Bi	ts	
Ref_rst1	0Ah	1111 1110	Ch8	Ch7	Ch6	Ch5	Ch4	Ch3	Ch2	Ch1	
Ref_rst2	0Bh	1111 1111	Ch16	Ch15	Ch14	Ch13	Ch12	Ch11	Ch10	Ch9	
Ch_hold1	0Ch	1111 1110	Ch8	Ch7	Ch6	Ch5	Ch4	Ch3	Ch2	Ch1	
Ch_hold2	0Dh	1111 1111	Ch16	Ch15	Ch14	Ch13	Ch12	Ch11	Ch10	Ch9	
Cal_hold1	0Eh	0000 0000	Ch8	Ch7	Ch6	Ch5	Ch4	Ch3	Ch2	Ch1	
Cal_hold2	0Fh	0000 0000	Ch16	Ch15	Ch14	Ch13	Ch12	Ch11	Ch10	Ch9	
Output1	10h	0000 0000	OU	T4	JO	JT3	OU	T2	OU	T1	
Output2	11h	0000 0000	OU	Т8	OU	T 7	OU	T6	OU	T5	
Output3	12h	0000 0000	OU	Г12	OU	T11	OU'	T10	OU	T9	
Output3	13h	0000 0000	OUT16 OUT15		T15	OU'	OUT14 OUT13				
Lock_mask	3Bh	0000 0000				LOCK	_MASK				
Force_en	41h	0001 0100	FEN	0	0	1	0	1	0	0	





## 8.2 Details

## 8.2.1 Sensitivity Control Register

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
02h	Sensitivity1	Ch2HL		Ch2M		Ch1HL		Ch1M	
03h	Sensitivity2	Ch4HL		Ch4M		Ch3HL		Ch3M	
04h	Sensitivity3	Ch6HL		Ch6M		Ch5HL		Ch5M	
05h	Sensitivity4	Ch8HL		Ch8M		Ch7HL		Ch7M	
06h	Sensitivity5	Ch10HL		Ch10M		Ch9HL		Ch9M	
07h	Sensitivity6	Ch12HL		Ch12M		Ch11HL		Ch11M	_
22h	Sensitivity7	Ch14HL		Ch14M		Ch13HL		Ch13M	
23h	Sensitivity8	Ch16HL		Ch16M		Ch15HL		Ch15M	

## **Description**

The sensitivity of channel 1 and 2 are adjustable by Sensitivity\_1 register. ChxM[2:0] allows various middle sensitivity and also the high and low sensitivities are decided with ChxHL. Be careful to use low sensitivity

because it is sensitive to environmental change.

Bit name	Reset	Fun	ction
		Middle sensitivity	
		<b>4</b> 000 : 0.50%	<b>4</b> 100 : 1.50%
ChxM[2:0]	011	<b>4</b> 001 : 0.70%	<b>4</b> 101 : 2.05%
		<b>4</b> 010 : 0.90%	<b>4</b> 110 : 2.55%
		<b>♣</b> 011 : 1.20%	<b>4</b> 111 : 3.55%
		High and Low sensitivity selection for	r channels
		0	1
		Low Sensitivity High Sensitivity	Low Sensitivity High Sensitivity
		<b>♣</b> 000 : 0.40% <b>♣</b> 000 : 0.6%	<b>4</b> 000 : 0.35% <b>4</b> 000 : 0.65%
		<b>↓</b> 001 : 0.55% <b>↓</b> 001 : 0.85%	<b>4</b> 001 : 0.50% <b>4</b> 001 : 0.90%
ChxHL	1	<b>↓</b> 010 : 0.70 % <b>↓</b> 010 : 1.10%	<b>4</b> 010 : 0.60% <b>4</b> 010 : 1.20%
		<b>↓</b> 011 : 0.95% <b>↓</b> 011 : 1.45%	<b>4</b> 011 : 0.85% <b>4</b> 100 : 1.60%
		<b>4</b> 100 : 1.20% <b>4</b> 100 : 1.85%	<b>1</b> 00 : 1.05% <b>1</b> 00 : 2.00%
		<b>4</b> 101 : 1.60% <b>4</b> 101 : 2.45%	<b>4</b> 101 : 1.40% <b>4</b> 101 : 2.65%
		<b>4</b> 110 : 2.05% <b>4</b> 110 : 3.05%	<b>1</b> 10: 1.80% <b>1</b> 10: 3.30%
		<b>4</b> 111 : 2.85% <b>4</b> 111 : 4.30%	<b>4</b> 111 : 2.45% <b>4</b> 111 : 4.65%

## 8.2.2 General Control Register1

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
08h	CTRL1	MS	FTC[1:0]		ILC	[1:0]		RTC[2:0]	

### Description

The calibration speed just after power on reset is very high during the time which is defined by FTC[1:0] to have a good adoption against unstable external environment.

Bit name	Reset value	Function
MS	0	Mode Selection





		0: auto alternate (fast/slow) mode
		1: fast mode
		First Touch Control
		00: 19 * 16 <sup>1</sup> * 1-Period (ms)
FTC[1:0]	01	01:37 * 16 * 1-Period (ms)
		10:56 * 16 * 1-Period (ms)
		11 : 74 * 16 * 1-Period (ms)
		Interrupt Level Control
		00: Interrupt is on middle or high output.
ILC[1:0]	00	01: Interrupt is on low or middle or high output.
		10: Interrupt is on middle or high output.
		11: Interrupt is on high output.
DTC[0.0]	011	Response Time Control
RTC[2:0]	011	Response period = $RTC[2:0] + 2$

## 8.2.3 General Control Register2

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
09h	CTRL2	0	0	MULTI	IMP_S EL	SRST	SLEEP	0	1

### **Description**

Single/Multi output mode is selected according to MULTI bit. For impedance, IMP\_SEL bit is used. All the digital blocks except analog and I2C block are reset when SRST is set. The SLEEP function allows getting very low current consumption when it is set. But the response time will be longer than normal operation. The bit0 and bit1 must be written with 0b'11 by host MCU.

Bit name	Reset	Function
		Single/Multiple Output Mode Select with FEN bit(0x41[7])
MULTI	0	0: Multiple Output Mode
		1: Single Output Mode
		Impedance Select
IMP_SEL	0	0: High Impedance
		1: Low Impedance
		Software Reset
SRST	0	0: Disable Software Reset
		1: Enable Software Reset
		Sleep Mode Enable
SLEEP	0	0: Disable Sleep Mode
		1: Enable Sleep Mode
Bit[1:0]	01	These bits must be written by 2b'11 during a system initialize phase. (refer
Би[1:0]	01	to the chapter 9 "initialize flow example")

## 8.2.4 Channel Reference Reset Control Register

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0Ah	Ref_rst1	Ch8	Ch7	Ch6	Ch5	Ch4	Ch3	Ch2	Ch1
0Bh	Ref_rst2	Ch16	Ch15	Ch14	Ch13	Ch12	Ch11	Ch10	Ch9

<sup>&</sup>lt;sup>1</sup> The number, 16 is the time control constant value





## **Description**

The reference value of each channel will be renewing when Chx is set.

Bit name	Reset	Function
Chx	1	0: Disable reference reset
Clix	1	1: Enable reference reset
Ch1	0	0: Disable reference reset
CIII		1: Enable reference reset

## 8.2.5 Channel Sensing Control Register

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0Ch	Ch_hold1	Ch8	Ch7	Ch6	Ch5	Ch4	Ch3	Ch2	Ch1
0D	Ch_hold2	Ch16	Ch15	Ch14	Ch13	Ch12	Ch11	Ch10	Ch9

## **Description**

The operation of each channel is independently available to control. A channel doesn't be worked and the calibration is paused when it is set.

Bit name	Reset Function			
Chy	Chx 1	0: Enable operation (sensing + calibration)		
Cnx		1: Hold operation (No sensing + Stop calibration)		
Ch1	0	0: Enable operation (sensing + calibration)		
CIII		1: Hold operation (No sensing + Stop calibration)		

## 8.2.6 Channel Calibration Control Register

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0Eh	Cal_hold1	Ch8	Ch7	Ch6	Ch5	Ch4	Ch3	Ch2	Ch1
0Fh	Cal_hold2	Ch16	Ch15	Ch14	Ch13	Ch12	Ch11	Ch10	Ch9

## **Description**

The calibration of each channel is independently available to control. Each channel is working even if a bit is set.

Bit name	Reset	Function
Chx	0	0: Enable reference calibration (sensing + calibration)
Clix	0	1: Disable reference calibration (sensing + No calibration)

## 8.2.7 Output Register

Type: R

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
10h	output1	OUT4[1:0]		OUT3[1:0]		OUT2[1:0]		OUT1[1:0]	
11h	output2	OUT8[1:0]		OUT7[1:0]		OUT6[1:0]		OUT5[1:0]	
12h	12h output3		OUT12[1:0]		OUT11[1:0]		OUT10[1:0]		9[1:0]
13h output3		OUT16[1:0]		OUT15[1:0]		OUT14[1:0]		OUT13[1:0]	

## **Description**

The each channel output of TSM16C is compressed with 2 bits. It has 3 level output information that is low, middle and high.





Bit name	Reset value	Function						
OUT1[1:0] ~ OUT16[1:0]	00	Output of channels 00: No output 01: low output 10: middle output 11: high output						

## 8.2.8 Lock Mask Register

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
3Bh	Lock_mask				LOCK	MASK			

Lock mask bits prevent the specific bits in TSM16C from changing in noise environments.

Bit name	Reset value	Function
LOCK_MASK	0000 0000	For applying MULTI bit(0x09[5]), Lock mask bits should be 8'h10100101

## 8.2.9 Touch Mode Register

Type: R/W

Address	Register Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
41h	Force_en	FEN	0	0	1	0	1	0	0

## **Description**

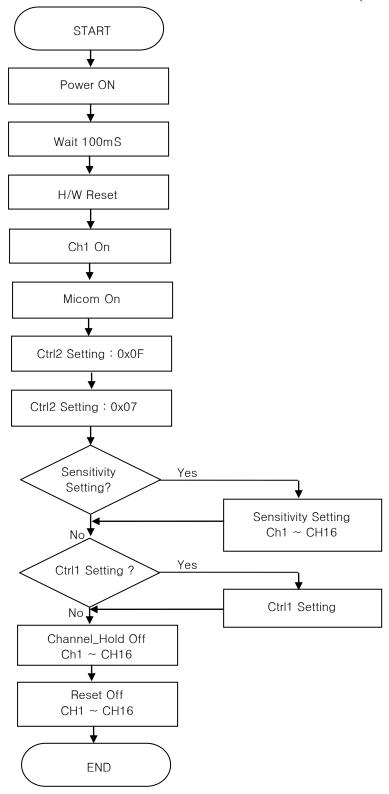
FEN bit selects the single and multi touch detection mode.

Bit name	Reset value	Function
FEN	0001 0100	For applying MULTI bit(0x09[5]), Lock mask bits should be 8'h10100101 and FEN bit should be 1'b1





# 9 Recommended TSM16C Initialize Flow (Example)

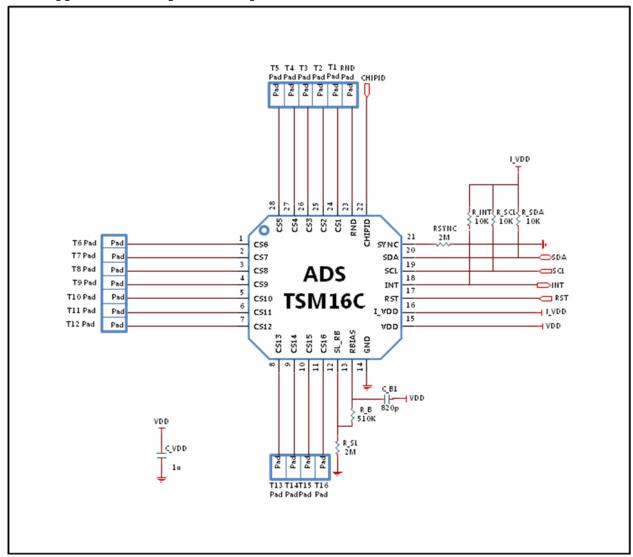






## 10 Recommended Circuit Diagram

## 10.1 Application Example in clean power environment



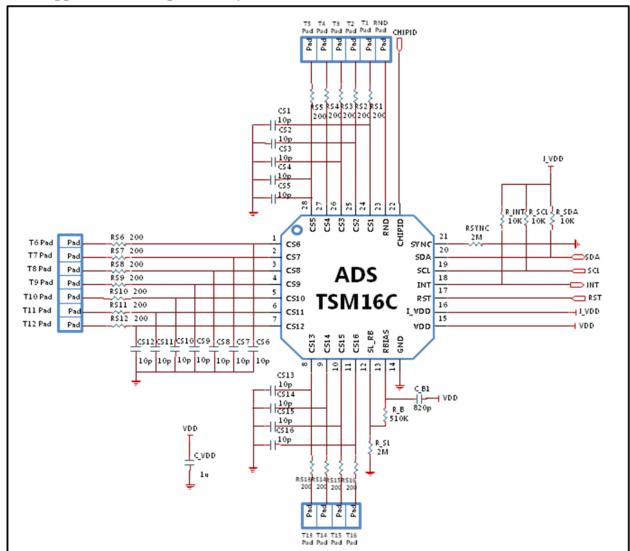
TSM16C Application Example Circuit (Clean power environment)

- ✓ In PCB layout, R\_B should not be placed on touch pattern. If not, C\_B has to be connected. The R\_B pattern should be routed as short as possible.
- ✓ The CS patterns also should be routed as short as possible and the width of line might be about 0.25mm.
- ✓ The capacitor that is between VDD and GND is an obligation. It should be located as close as possible from TSM16C.
- $\checkmark$  The CS pattern routing should be formed by bottom metal (opposite metal of touch PAD).
- ✓ The empty space of PCB must be filled with GND pattern to strengthen GND pattern and to prevent external noise from interfere with sensing frequency.
- ✓ The TSM16C is reset if RST Pin is high. (See 6.5 Reset implementation chapter)





## **10.2** Application Example in noisy environment



TSM16C Application Example Circuit (Noisy environment)

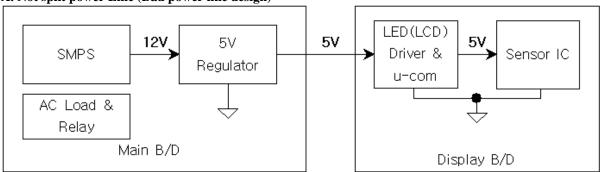
- The VDD periodic voltage ripple over 50mV and the ripple frequency is lower than 10 kHz can cause wrong sensitivity calibration. To prevent above problem, power (VDD, GND) line of touch circuit should be separated from other circuit. Especially LED driver power line or digital switching circuit power line certainly should be treated to be separated from touch circuit.
- The smaller R\_B is recommended in noisy environments.





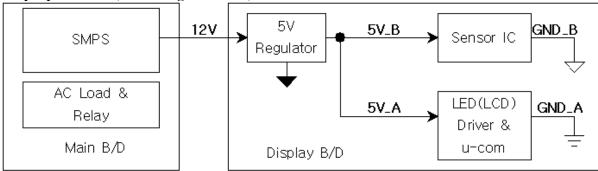
## 10.3 Example – Power Line Split Strategy PCB Layout

## A. Not split power Line (Bad power line design)

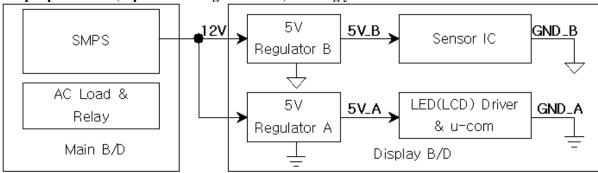


- The noise that is generated by AC load or relay can be loaded at 5V power line.
- A big inductance might be appeared in case of the connection line between main board and display board is too long, moreover the voltage ripple could be generated by LED (LCD) display driver at VDD (5V).

## B. Split power Line (One 5V regulator used) - Recommended



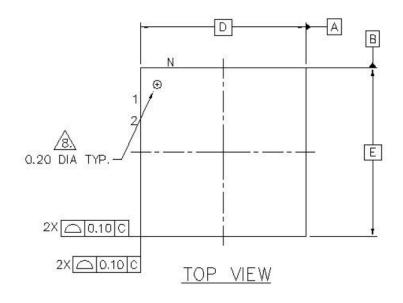
## C. Split power Line (Separated 5V regulator used) – Strongly recommended

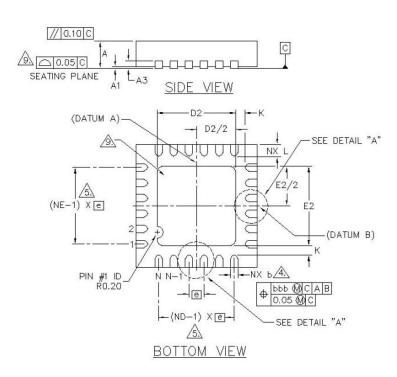




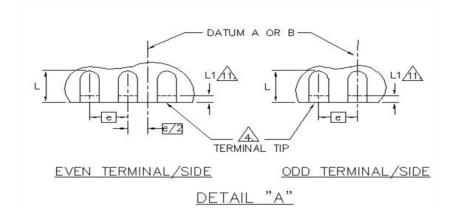
## 11 MECHANICAL DRAWING

#### 11.1 **Mechanical Drawing of TSM16C (28 QFN)**









5	0.40mm LEAD PITCH							NI DIMEN	ISIONS			
M B	VA	RIATION	Α	VA	RIATION	В	N <sub>D</sub> T <sub>E</sub>	B	MINI	I NOM I		No <sub>T</sub>
L	MIN.	NOM. 0.40 BSC	MAX.	MIN.	NOM. 0.40 BSC	MAX.	1 5	A	0.70	0.75	MAX. 0.80	E
e N		28		2	32		3	A1 A3	0.00	0.02   0.20 REF.	0.05	
ND NE		7			8		<u>\$</u>	0	0		12	2
L	0.35	0.40	0.45	0.35	0.40	0.45	13	K		0.20 MIN.		
b	0.15	0.20	0.25	0.15	0.20	0.25	A	D	į.	4.0 BSC		
D2	2.50	2.60	2.70	2.50	2.60	2.70		E		4.0 BSC		1 0
E2	2.50	2,60	2.70	2,50	2,60	2.70		L1	0.1	15 mm M <i>A</i>	łΧ	1

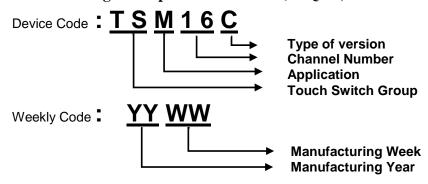
### NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORME TO ASME Y14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS,  $\theta$  IS IN DEGREES.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.
- 4. DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION & SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
- S ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- 6. MAX. PACKAGE WARPAGE IS 0.05 mm.
- 7. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
- 8 PIN #1 ID ON TOP WILL BE LASER MARKED.
- S BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 10. THIS DRAWING CONFORMES TO JEDEC REGISTERED OUTLINE MO-220
- 1 DEPENDING ON THE METHOD OF LEAD TERMINATION AT THE EDGE OF THE PACKAGE, PULLBACK (L1) MAYBE PRESENT
- 12 PULLBACK DESIGN OPTION IS FOR 0.50mm NOMINAL LANDLENGTH ONLY.



## 12 MARKING DESCRIPTION

## 12.1 Marking Description of TSM16C (28 QFN)







N	$\cap$	TE	٦.

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